



- ☐ Drafts
- ☐ Pending
- ☒ Active
 - ☒ L1: (6) substrate and bond near layer and encasing near layer
 - ☒ L2: (42) substrate and bond near layer and anodic near bond\$3
 - ☒ L3: (327) substrate and (bond near layer bonding near layer) and anodic near bond\$3
 - ☒ L4: (163) substrate and (bond adj layer bonding adj layer) and anodic near bond\$3
 - ☒ L5: (1712) substrate and (bond adj layer bonding adj layer metal) and anodic near bond\$3
 - ☒ L6: (163) substrate and (bond adj layer bonding adj layer) and anodic near bond\$3
 - ☒ L7: (1) ("6806557").PN.
- ☐ Failed
- ☐ Saved
- ☐ Favorites
- ☐ Tagged (0)
- ☐ UDC
- ☐ Queue
- ☐ Trash

 US-PGPUB; USPAT; USOCR; EPO; JPO ☐ Plurals

 Default operator:
☒ Highlight all hit terms initially

substrate and (bond adj layer bonding adj layer) and anodic near bond\$3

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
1	<input type="checkbox"/>	<input type="checkbox"/>	US 20050170546 A1	20050804	28	Metod for making a micromechanical device by using a sacrificial substrate	438/48	438/68
2	<input type="checkbox"/>	<input type="checkbox"/>	US 20050167752 A1	20050804	12	Electronic apparatuses, silicon-on-insulator integrated circuits, and fabrication methods	257/347	438/149
3	<input type="checkbox"/>	<input type="checkbox"/>	US 20050146046 A1	20050707	13	Method for making probes for atomic force microscopy	257/773	438/14; 438/460
4	<input type="checkbox"/>	<input type="checkbox"/>	US 20050139996 A1	20050630	18	Apparatus and method integrating an electro-osmotic pump and microchannel assembly into a die package	257/712	257/698; 257/714; 257/784
5	<input type="checkbox"/>	<input type="checkbox"/>	US 20050132750 A1	20050623	13	Method for joining at least a first member and a second member, lithographic apparatus and device manufacturing method, as well as a device manufa	65/40	101/463.1; 378/34
6	<input type="checkbox"/>	<input type="checkbox"/>	US 20050111797 A1	20050526	48	Device package and methods for the fabrication and testing thereof	385/93	
7	<input type="checkbox"/>	<input type="checkbox"/>	US 20050110157 A1	20050526	48	Device package and method for the fabrication and testing thereof	257/776	257/712; 257/98; 257/90
8	<input type="checkbox"/>	<input type="checkbox"/>	US 20050077633 A1	20050414	15	Anodic bonding structure, fabricating method thereof, and method of manufacturing optical scanner using the same	257/782	438/455
9	<input type="checkbox"/>	<input type="checkbox"/>	US 20050063071 A1	20050324	19	Methods to make diffractive optical elements	359/742	
10	<input type="checkbox"/>	<input type="checkbox"/>	US 20050062163 A1	20050324	12	Electronic apparatus, silicon-on-insulator integrated circuits, and fabrication methods	257/758	
11	<input type="checkbox"/>	<input type="checkbox"/>	US 20050045973 A1	20050303	8	Micromechanical cap structure and a corresponding production method	257/414	